

IN THE CLAIMS

1. - 2. (Cancelled)

3. (Currently Amended) A method of assembling a connector, comprising:

providing a plurality of connector slices, each connector slice comprising an electrically insulating body of a first thickness, the electrically insulating body having first and second major surfaces, and further having a plurality of through-holes providing openings between the first and second major surfaces;

stacking the plurality of connector slices, one atop another, in alignment such that major surfaces are facing one another and each through-hole of each connector slice is coaxially aligned with the corresponding through-holes of the other connector slices, and such that the stack so formed has a first predetermined height; and

adhering at least one pair of the plurality of stacked connector slices to each other; **and**

**disposing a conductor that is surrounded by a dielectric layer into at least one of the plurality of through-holes;**

~~wherein each of the through-holes are adapted to receive a conductor; and~~

wherein adhering comprises one of the group consisting of disposing a low viscosity glue between the at least one pair of the first plurality of stacked connector slices, and disposing an adhesive sheet between the at least one pair of the plurality of stacked connector slices.

4. -14. (Cancelled)

15. (Currently Amended) A method of assembling a connector, comprising:

providing a plurality of connector slices, each connector slice comprising an electrically insulating body of a first thickness, the electrically insulating body having first and second major surfaces, and further having a plurality of through-holes providing openings between the first and second major surfaces; ~~and~~

stacking the plurality of connector slices, one atop another, in alignment such that major surfaces are facing one another and each through-hole of each connector slice is coaxially aligned with the corresponding through-holes of the other connector slices, and such that the stack so formed has a first predetermined height; and

disposing a conductor that is surrounded by a dielectric layer into at least one of the plurality of through-holes;

wherein each of the through-holes are adapted to receive a conductor; and further comprising disposing a tight-sheet between at least one pair of the stacked connector slices, the tight-sheet having through-holes coaxially aligned with the through-holes of the stacked connector slices.

16. (Original) The method of Claim 15, wherein the tight-sheet comprises a flex material.

17. (Original) The method of Claim 15, wherein the tight-sheet comprises a sheet of rigid material, the through-holes of the rigid material having an inner circumference that is less than an inner circumference of the through-holes of the stacked connector slices.

18. (Cancelled)

19. (Previously Presented) A method of assembling a connector, comprising:

providing a plurality of connector slices, each connector slice comprising an electrically insulating body of a first thickness, the electrically insulating body having first and second major surfaces, and further having a plurality of through-holes providing openings between the first and second major surfaces; and

stacking the plurality of connector slices, one atop another, in alignment such that major surfaces are facing one another and each through-hole of each connector slice is coaxially aligned with the corresponding through-holes of the other connector slices, and such that the stack so formed has a first predetermined height;

wherein each of the through-holes are adapted to receive a conductor; and further comprising providing an electrically conductive coating in at least a portion of the through-holes of the plurality of connector slices; and disposing a conductive sheet between a pair of the plurality of stacked connector slices.

20. (Original) The method of Claim 19, further comprising inserting a conductor with a dielectric coating into a conductively coated through-hole.

21. (New) The method of Claim 3, wherein the conductor surrounded by the dielectric layer further includes a conductive shield surrounding the dielectric layer.

22. (New) The method of Claim 21. wherein the conductive shield is surrounded by an insulating layer.

23. (New) The method of Claim 3, further comprising, disposing a twinaxial cable segment into at least one of the through-holes.

24. (New) The method of Claim 15, wherein the conductor surrounded by the dielectric layer further includes a conductive shield surrounding the dielectric layer.

25. (New) The method of Claim 24. wherein the conductive shield is surrounded by an insulating layer.

26. (New) The method of Claim 15, further comprising, disposing a twinaxial cable segment into at least one of the through-holes.